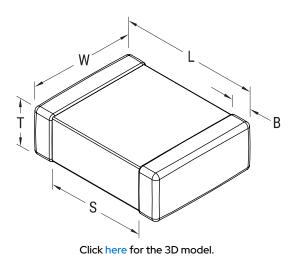


## C2220X333G1TACTU

Aliases (C2220X333G1TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 0.033 uF, 2%, 100 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	130 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	2220
L	5.9mm +/-0.75mm
W	5mm +/-0.4mm
Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm

Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm
Packaging Specifications	

1000

Packaging

Packaging Quantity

T&R, 180mm, Plastic Tape

Specifications		
Capacitance	0.033 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	2%	
Voltage DC	100 VDC	
Dielectric Withstanding Voltage	250 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	30.303 GOhms	

Insulation Resistance	30.303 GOnms

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